



SN74LVC1G125 Single Bus Buffer Gate With 3-State Output

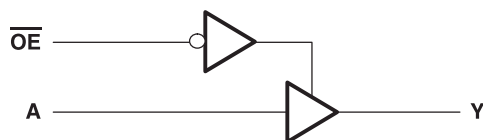
1 Features

- Available in the Ultra Small 0.64-mm² Package (DPW) With 0.5-mm Pitch
- Supports 5-V V_{CC} Operation
- Inputs Accept Voltages to 5.5 V
- Provides Down Translation to V_{CC}
- Max t_{pd} of 3.7 ns at 3.3 V
- Low Power Consumption, 10- μ A Max I_{CC}
- ± 24 -mA Output Drive at 3.3 V
- I_{off} Supports Live Insertion, Partial-Power-Down Mode, and Back-Drive Protection
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)

2 Applications

- Cable Modem Termination System
- High-Speed Data Acquisition and Generation
- Military: Radar and Sonar
- Motor Control: High-Voltage
- Power Line Communication Modem
- SSD: Internal or External
- Video Broadcasting and Infrastructure: Scalable Platform
- Video Broadcasting: IP-Based Multi-Format Transcoder
- Video Communications System

4 Simplified Schematic



3 Description

This bus buffer gate is designed for 1.65-V to 5.5-V V_{CC} operation.

The SN74LVC1G125 device is a single line driver with a 3-state output. The output is disabled when the output-enable (\overline{OE}) input is high.

The CMOS device has high output drive while maintaining low static power dissipation over a broad V_{CC} operating range.

The SN74LVC1G125 device is available in a variety of packages including the ultra-small DPW package with a body size of 0.8 mm \times 0.8 mm.

Device Information⁽¹⁾

| DEVICE NAME | PACKAGE | BODY SIZE (NOM) |
|--------------|------------|--------------------------|
| SN74LVC1G125 | SOT-23 (5) | 2.90 mm \times 1.60 mm |
| | SC70 (5) | 2.00 mm \times 1.25 mm |
| | SON (6) | 1.45 mm \times 1.00 mm |
| | DSBGA (5) | 1.40 mm \times 0.90 mm |
| | X2SON (4) | 0.80 mm \times 0.80 mm |

(1) For all available packages, see the orderable addendum at the end of the data sheet.



Table of Contents

| | | | |
|---|----------|--|-----------|
| 1 Features | 1 | 9 Detailed Description | 10 |
| 2 Applications | 1 | 9.1 Overview | 10 |
| 3 Description | 1 | 9.2 Functional Block Diagram | 10 |
| 4 Simplified Schematic | 1 | 9.3 Feature Description | 10 |
| 5 Revision History | 2 | 9.4 Device Functional Modes | 10 |
| 6 Pin Configuration and Functions | 3 | 10 Application and Implementation | 11 |
| 7 Specifications | 4 | 10.1 Application Information | 11 |
| 7.1 Absolute Maximum Ratings | 4 | 10.2 Typical Application | 11 |
| 7.2 Handling Ratings | 4 | 11 Power Supply Recommendations | 12 |
| 7.3 Recommended Operating Conditions | 5 | 12 Layout | 12 |
| 7.4 Thermal Information | 5 | 12.1 Layout Guidelines | 12 |
| 7.5 Electrical Characteristics | 6 | 12.2 Layout Example | 12 |
| 7.6 Switching Characteristics, $C_L = 15\text{ pF}$ | 6 | 13 Device and Documentation Support | 13 |
| 7.7 Switching Characteristics, -40°C to 85°C | 6 | 13.1 Trademarks | 13 |
| 7.8 Switching Characteristics, -40°C to 125°C | 7 | 13.2 Electrostatic Discharge Caution | 13 |
| 7.9 Operating Characteristics | 7 | 13.3 Glossary | 13 |
| 7.10 Typical Characteristics | 7 | 14 Mechanical, Packaging, and Orderable Information | 13 |
| 8 Parameter Measurement Information | 8 | | |

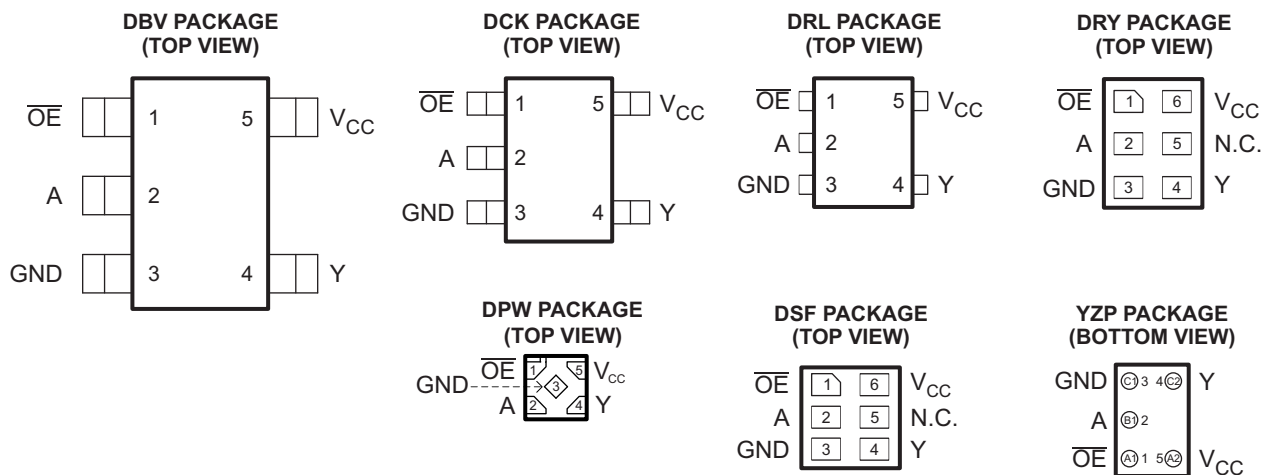
5 Revision History

| Changes from Revision S (April 2014) to Revision T | Page |
|--|------|
| • Updated Device Information table. | 1 |
| • Removed PREVIEW status from DPW Pin Out drawing. | 3 |

| Changes from Revision R (April 2013) to Revision S | Page |
|--|------|
| • Added Applications. | 1 |
| • Added Pin Functions table. | 3 |
| • Updated Handling Ratings table. | 4 |
| • Added Thermal Information table. | 5 |
| • Added Typical Characteristics. | 7 |
| • Added Detailed Description section. | 10 |
| • Added Application and Implementation section. | 11 |
| • Added Power Supply Recommendations section. | 12 |
| • Added Layout section. | 12 |

| Changes from Revision Q (November 2012) to Revision R | Page |
|---|------|
| • Added Device Information table. | 1 |
| • Moved T_{stg} to Handling Ratings table. | 4 |
| • Added -40°C to 125°C Temperature range to Electrical Characteristics. | 6 |
| • Added Switching Characteristics for -40°C to 125°C temperature range. | 7 |

6 Pin Configuration and Functions



N.C. – No internal connection

See mechanical drawings for dimensions.

Pin Functions

| NAME | PIN | | | | | DESCRIPTION |
|-----------------|---------------|----------|-----|-----|--|---------------|
| | DRL, DCK, DBV | DRY, DSF | DPW | YZP | | |
| \overline{OE} | 1 | 1 | 1 | A1 | | Input |
| A | 2 | 2 | 2 | B1 | | Input |
| GND | 3 | 3 | 3 | C1 | | Ground |
| Y | 4 | 4 | 4 | C2 | | Output |
| V_{CC} | 5 | 6 | 5 | A2 | | Power pin |
| NC | – | 5 | – | – | | Not connected |

7 Specifications

7.1 Absolute Maximum Ratings⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

| | | MIN | MAX | UNIT |
|----------|---|-----------|----------------|------|
| V_{CC} | Supply voltage range | –0.5 | 6.5 | V |
| V_I | Input voltage range ⁽²⁾ | –0.5 | 6.5 | V |
| V_O | Voltage range applied to any output in the high-impedance or power-off state ⁽²⁾ | –0.5 | 6.5 | V |
| V_O | Voltage range applied to any output in the high or low state ⁽²⁾⁽³⁾ | –0.5 | $V_{CC} + 0.5$ | V |
| I_{IK} | Input clamp current | $V_I < 0$ | –50 | mA |
| I_{OK} | Output clamp current | $V_O < 0$ | –50 | mA |
| I_O | Continuous output current | | ±50 | mA |
| | Continuous current through V_{CC} or GND | | ±100 | mA |

- (1) Stresses beyond those listed under [Absolute Maximum Ratings](#) may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under [Recommended Operating](#) is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.
- (3) The value of V_{CC} is provided in the [Recommended Operating](#) table.

7.2 Handling Ratings

| | | | MIN | MAX | UNIT |
|--------------------|---------------------------|--|-----|------|------|
| T _{stg} | Storage temperature range | | −65 | 150 | °C |
| V _(ESD) | Electrostatic discharge | Human body model (HBM), per ANSI/ESDA/JEDEC JS-001, all pins ⁽¹⁾ | 0 | 2000 | V |
| | | Charged device model (CDM), per JEDEC specification JESD22-C101, all pins ⁽²⁾ | 0 | 1000 | |

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
- (2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

7.3 Recommended Operating Conditions⁽¹⁾

| | | | MIN | MAX | UNIT |
|-----------------|------------------------------------|---|------------------------|------------------------|------|
| V _{CC} | Supply voltage | Operating | 1.65 | 5.5 | V |
| | | Data retention only | 1.5 | | |
| V _{IH} | High-level input voltage | V _{CC} = 1.65 V to 1.95 V | 0.65 × V _{CC} | | V |
| | | V _{CC} = 2.3 V to 2.7 V | 1.7 | | |
| | | V _{CC} = 3 V to 3.6 V | 2 | | |
| | | V _{CC} = 4.5 V to 5.5 V | 0.7 × V _{CC} | | |
| V _{IL} | Low-level input voltage | V _{CC} = 1.65 V to 1.95 V | | 0.35 × V _{CC} | V |
| | | V _{CC} = 2.3 V to 2.7 V | | 0.7 | |
| | | V _{CC} = 3 V to 3.6 V | | 0.8 | |
| | | V _{CC} = 4.5 V to 5.5 V | | 0.3 × V _{CC} | |
| V _I | Input voltage | | 0 | 5.5 | V |
| V _O | Output voltage | | 0 | V _{CC} | V |
| I _{OH} | High-level output current | V _{CC} = 1.65 V | | –4 | mA |
| | | V _{CC} = 2.3 V | | –8 | |
| | | V _{CC} = 3 V | | –16 | |
| | | | | –24 | |
| | | V _{CC} = 4.5 V | | –32 | |
| I _{OL} | Low-level output current | V _{CC} = 1.65 V | | 4 | mA |
| | | V _{CC} = 2.3 V | | 8 | |
| | | V _{CC} = 3 V | | 16 | |
| | | | | 24 | |
| | | V _{CC} = 4.5 V | | 32 | |
| Δt/Δv | Input transition rise or fall rate | V _{CC} = 1.8 V ± 0.15 V, 2.5 V ± 0.2 V | | 20 | ns/V |
| | | V _{CC} = 3.3 V ± 0.3 V | | 10 | |
| | | V _{CC} = 5 V ± 0.5 V | | 5 | |
| T _A | Operating free-air temperature | | –40 | 125 | °C |

(1) All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number [SCBA004](#).

7.4 Thermal Information

| THERMAL METRIC ⁽¹⁾ | | SN74LVC1G125 | | | | | | UNIT |
|-------------------------------|--|--------------|--------|--------|--------|--------|--------|------|
| | | DBV | DCK | DRL | DRY | YZP | DPW | |
| | | 5 PINS | 5 PINS | 5 PINS | 6 PINS | 5 PINS | 4 PINS | |
| R _{θJA} | Junction-to-ambient thermal resistance | 229 | 278 | 243 | 439 | 130 | 340 | °C/W |
| R _{θJC(top)} | Junction-to-case (top) thermal resistance | 164 | 93 | 78 | 277 | 54 | 215 | |
| R _{θJB} | Junction-to-board thermal resistance | 62 | 65 | 78 | 271 | 51 | 294 | |
| Ψ _{JT} | Junction-to-top characterization parameter | 44 | 2 | 10 | 84 | 1 | 41 | |
| Ψ _{JB} | Junction-to-board characterization parameter | 62 | 64 | 77 | 271 | 50 | 294 | |
| R _{θJC(bot)} | Junction-to-case (bottom) thermal resistance | – | – | – | – | – | 250 | |

(1) For more information about traditional and new thermal metrics, see the *IC Package Thermal Metrics* application report, [SPRA953](#).

7.5 Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER | | TEST CONDITIONS | V _{CC} | –40 °C to 85 °C | | –40 °C to 125 °C | | UNIT |
|------------------|-----------------------------|--|-----------------|-----------------------|------------------------|-----------------------|------------------------|------|
| | | | | MIN | TYP ⁽¹⁾ MAX | MIN | TYP ⁽¹⁾ MAX | |
| V _{OH} | | I _{OH} = –100 μA | 1.65 V to 5.5 V | V _{CC} – 0.1 | | V _{CC} – 0.1 | | V |
| | | I _{OH} = –4 mA | 1.65 V | 1.2 | | 1.2 | | |
| | | I _{OH} = –8 mA | 2.3 V | 1.9 | | 1.9 | | |
| | | I _{OH} = –16 mA | 3 V | 2.4 | | 2.4 | | |
| | | I _{OH} = –24 mA | | 2.3 | | 2.3 | | |
| | | I _{OH} = –32 mA | 4.5 V | 3.8 | | 3.8 | | |
| V _{OL} | | I _{OL} = 100 μA | 1.65 V to 5.5 V | 0.1 | | 0.1 | | V |
| | | I _{OL} = 4 mA | 1.65 V | 0.45 | | 0.45 | | |
| | | I _{OL} = 8 mA | 2.3 V | 0.3 | | 0.3 | | |
| | | I _{OL} = 16 mA | 3 V | 0.4 | | 0.4 | | |
| | | I _{OL} = 24 mA | | 0.55 | | 0.55 | | |
| | | I _{OL} = 32 mA | 4.5 V | 0.55 | | 0.55 | | |
| I _I | A or \overline{OE} inputs | V _I = 5.5 V or GND | 0 to 5.5 V | ±5 | | ±5 | | μA |
| I _{off} | | V _I or V _O = 5.5 V | 0 | ±10 | | ±10 | | μA |
| I _{OZ} | | V _O = 0 to 5.5 V | 3.6 V | 10 | | 10 | | μA |
| I _{CC} | | V _I = 5.5 V or GND, I _O = 0 | 1.65 V to 5.5 V | 10 | | 10 | | μA |
| ΔI _{CC} | | One input at V _{CC} – 0.6 V, Other inputs at V _{CC} or GND | 3 V to 5.5 V | 500 | | 500 | | μA |
| C _I | | V _I = V _{CC} or GND | 3.3 V | 4 | | 4 | | pF |

(1) All typical values are at V_{CC} = 3.3 V, T_A = 25°C.

7.6 Switching Characteristics, C_L = 15 pF

over recommended operating free-air temperature range of –40°C to 85°C, C_L = 15 pF (unless otherwise noted)
(see Figure 3)

| PARAMETER | FROM (INPUT) | TO (OUTPUT) | V _{CC} = 1.8 V ± 0.15 V | | V _{CC} = 2.5 V ± 0.2 V | | V _{CC} = 3.3 V ± 0.3 V | | V _{CC} = 5 V ± 0.5 V | | UNIT |
|-----------------|--------------|-------------|----------------------------------|-----|---------------------------------|-----|---------------------------------|-----|-------------------------------|-----|------|
| | | | MIN | MAX | MIN | MAX | MIN | MAX | MIN | MAX | |
| t _{pd} | A | Y | 1.9 | 6.9 | 0.7 | 4.6 | 0.6 | 3.7 | 0.5 | 3.4 | ns |

7.7 Switching Characteristics, –40°C to 85°C

over recommended operating free-air temperature range –40°C to 85°C, C_L = 30 pF or 50 pF (unless otherwise noted)
(see Figure 4)

| PARAMETER | FROM (INPUT) | TO (OUTPUT) | V _{CC} = 1.8 V ± 0.15 V | | V _{CC} = 2.5 V ± 0.2 V | | V _{CC} = 3.3 V ± 0.3 V | | V _{CC} = 5 V ± 0.5 V | | UNIT |
|------------------|-----------------|-------------|----------------------------------|------|---------------------------------|-----|---------------------------------|-----|-------------------------------|-----|------|
| | | | MIN | MAX | MIN | MAX | MIN | MAX | MIN | MAX | |
| t _{pd} | A | Y | 2.8 | 9 | 1.2 | 5.5 | 1 | 4.5 | 1 | 4 | ns |
| t _{en} | \overline{OE} | Y | 3.3 | 10.1 | 1.5 | 6.6 | 1 | 5.3 | 1 | 5 | ns |
| t _{dis} | \overline{OE} | Y | 1.3 | 9.2 | 1 | 5 | 1 | 5 | 1 | 4.2 | ns |

7.8 Switching Characteristics, –40°C to 125°C

over recommended operating free-air temperature range –40°C to 125°C, $C_L = 30$ pF or 50 pF (unless otherwise noted) (see Figure 4)

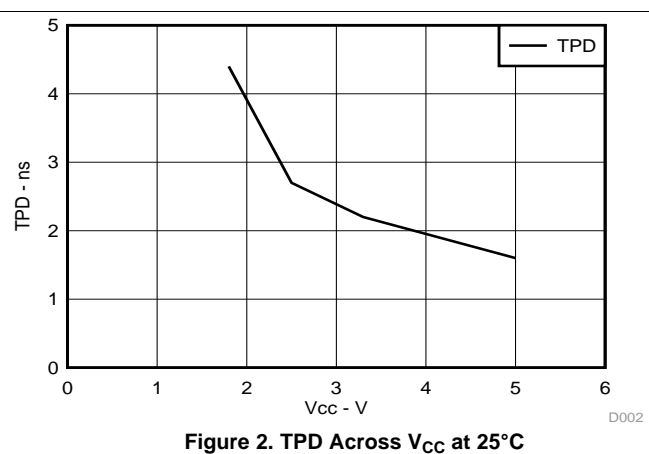
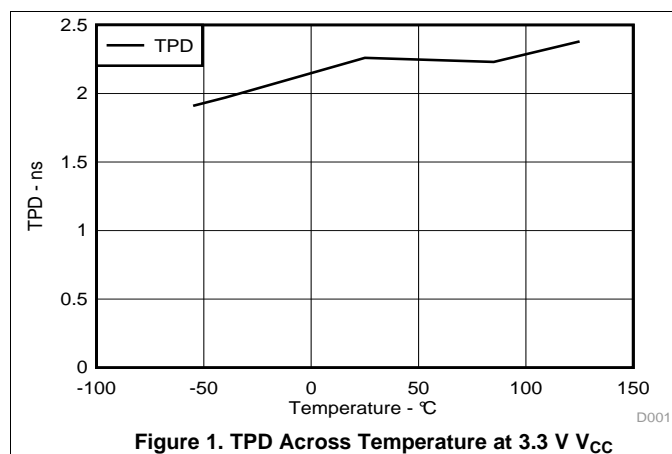
| PARAMETER | FROM (INPUT) | TO (OUTPUT) | $V_{CC} = 1.8\text{ V} \pm 0.15\text{ V}$ | | $V_{CC} = 2.5\text{ V} \pm 0.2\text{ V}$ | | $V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$ | | $V_{CC} = 5\text{ V} \pm 0.5\text{ V}$ | | UNIT |
|-----------|-----------------|----------------|---|------|--|-----|--|-----|--|-----|------|
| | | | MIN | MAX | MIN | MAX | MIN | MAX | MIN | MAX | |
| t_{pd} | A | Y | 2.8 | 9.3 | 1.2 | 5.8 | 1 | 4.7 | 1 | 4.2 | ns |
| t_{en} | \overline{OE} | Y | 3.3 | 10.4 | 1.5 | 6.9 | 1 | 5.6 | 1 | 5.2 | ns |
| t_{dis} | \overline{OE} | Y | 1.3 | 9.3 | 1 | 5.2 | 1 | 5.2 | 1 | 4.4 | ns |

7.9 Operating Characteristics

$T_A = 25^\circ\text{C}$

| PARAMETER | | | TEST CONDITIONS | $V_{CC} = 1.8\text{ V}$ | $V_{CC} = 2.5\text{ V}$ | $V_{CC} = 3.3\text{ V}$ | $V_{CC} = 5\text{ V}$ | UNIT |
|-----------|-------------------------------|------------------|---------------------|-------------------------|-------------------------|-------------------------|-----------------------|------|
| | | | | TYP | TYP | TYP | TYP | |
| C_{pd} | Power dissipation capacitance | Outputs enabled | $f = 10\text{ MHz}$ | 18 | 18 | 19 | 21 | pF |
| | | Outputs disabled | | 2 | 2 | 2 | 4 | |

7.10 Typical Characteristics

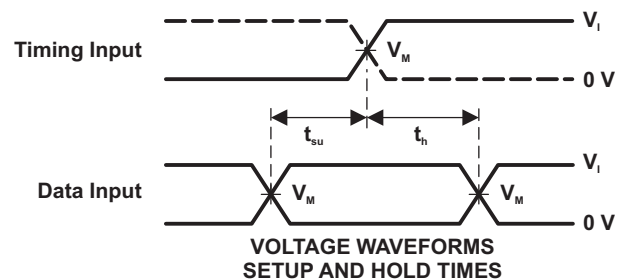


8 Parameter Measurement Information



| TEST | S1 |
|-------------------|------------|
| t_{PLH}/t_{PHL} | Open |
| t_{PLZ}/t_{PZL} | V_{LOAD} |
| t_{PHZ}/t_{PZH} | GND |

| V_{CC} | INPUTS | | V_M | V_{LOAD} | C_L | R_L | V_{Δ} |
|----------------------------------|----------|----------------------|------------|-------------------|-------|--------------|--------------|
| | V_I | t_i/t_f | | | | | |
| $1.8\text{ V} \pm 0.15\text{ V}$ | V_{CC} | $\leq 2\text{ ns}$ | $V_{CC}/2$ | $2 \times V_{CC}$ | 15 pF | 1 M Ω | 0.15 V |
| $2.5\text{ V} \pm 0.2\text{ V}$ | V_{CC} | $\leq 2\text{ ns}$ | $V_{CC}/2$ | $2 \times V_{CC}$ | 15 pF | 1 M Ω | 0.15 V |
| $3.3\text{ V} \pm 0.3\text{ V}$ | 3 V | $\leq 2.5\text{ ns}$ | 1.5 V | 6 V | 15 pF | 1 M Ω | 0.3 V |
| $5\text{ V} \pm 0.5\text{ V}$ | V_{CC} | $\leq 2.5\text{ ns}$ | $V_{CC}/2$ | $2 \times V_{CC}$ | 15 pF | 1 M Ω | 0.3 V |



- NOTES:
- C_L includes probe and jig capacitance.
 - Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 - All input pulses are supplied by generators having the following characteristics: PRR $\leq 10\text{ MHz}$, $Z_o = 50\ \Omega$.
 - The outputs are measured one at a time, with one transition per measurement.
 - t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - t_{PZL} and t_{PZH} are the same as t_{en} .
 - t_{PLH} and t_{PHL} are the same as t_{pd} .
 - All parameters and waveforms are not applicable to all devices.

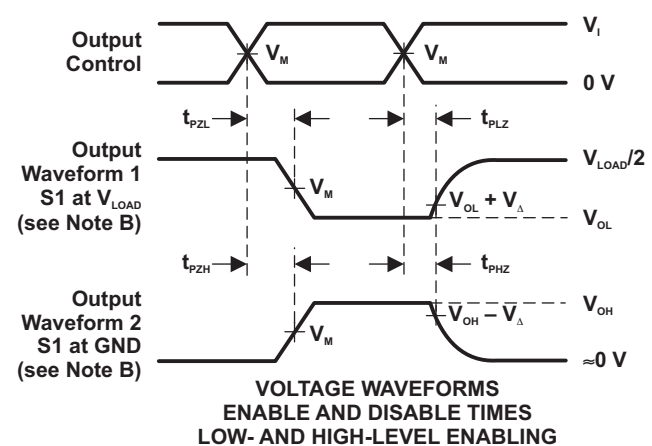
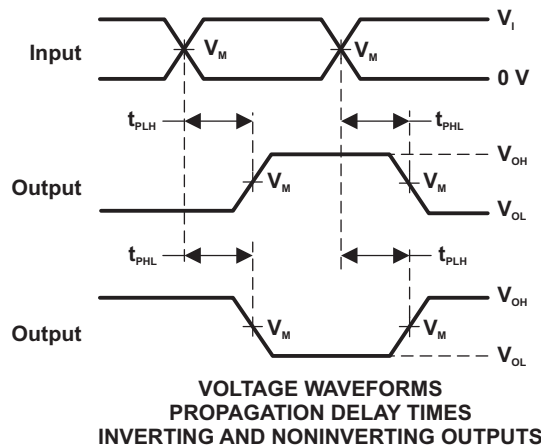
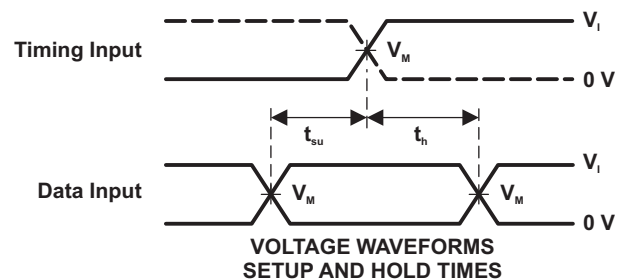
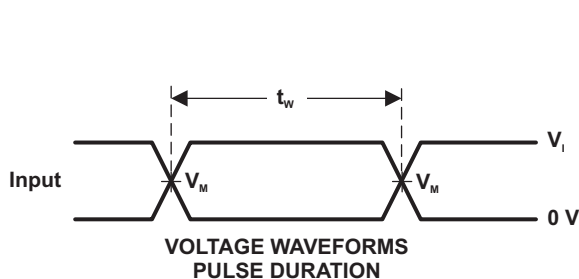
Figure 3. Load Circuit and Voltage Waveforms

Parameter Measurement Information (continued)



| TEST | S1 |
|-------------------|------------|
| t_{PLH}/t_{PHL} | Open |
| t_{PLZ}/t_{PZL} | V_{LOAD} |
| t_{PHZ}/t_{PZH} | GND |

| V_{CC} | INPUTS | | V_M | V_{LOAD} | C_L | R_L | V_{Δ} |
|----------------------------------|----------|----------------------|------------|-------------------|-------|--------------|--------------|
| | V_I | t_r/t_f | | | | | |
| $1.8\text{ V} \pm 0.15\text{ V}$ | V_{CC} | $\leq 2\text{ ns}$ | $V_{CC}/2$ | $2 \times V_{CC}$ | 30 pF | 1 k Ω | 0.15 V |
| $2.5\text{ V} \pm 0.2\text{ V}$ | V_{CC} | $\leq 2\text{ ns}$ | $V_{CC}/2$ | $2 \times V_{CC}$ | 30 pF | 500 Ω | 0.15 V |
| $3.3\text{ V} \pm 0.3\text{ V}$ | 3 V | $\leq 2.5\text{ ns}$ | 1.5 V | 6 V | 50 pF | 500 Ω | 0.3 V |
| $5\text{ V} \pm 0.5\text{ V}$ | V_{CC} | $\leq 2.5\text{ ns}$ | $V_{CC}/2$ | $2 \times V_{CC}$ | 50 pF | 500 Ω | 0.3 V |



- NOTES:
- C_L includes probe and jig capacitance.
 - Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 - All input pulses are supplied by generators having the following characteristics: $PRR \leq 10\text{ MHz}$, $Z_o = 50\ \Omega$.
 - The outputs are measured one at a time, with one transition per measurement.
 - t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - t_{PZL} and t_{PZH} are the same as t_{on} .
 - t_{PLH} and t_{PHL} are the same as t_{pd} .
 - All parameters and waveforms are not applicable to all devices.

Figure 4. Load Circuit and Voltage Waveforms

9 Detailed Description

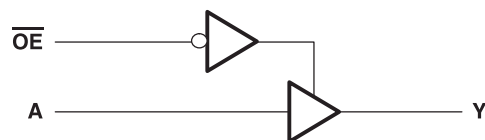
9.1 Overview

The SN74LVC1G125 device contains one buffer gate device with output enable control and performs the Boolean function $Y = A$. This device is fully specified for partial-power-down applications using I_{off} . The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The DPW package technology is a major breakthrough in IC packaging. Its tiny 0.64 mm square footprint saves significant board space over other package options while still retaining the traditional manufacturing friendly lead pitch of 0.5 mm.

9.2 Functional Block Diagram



9.3 Feature Description

- Wide operating voltage range
 - Operates from 1.65 V to 5.5 V
- Allows down voltage translation
- Inputs accept voltages to 5.5 V
- I_{off} feature allows voltages on the inputs and outputs, when V_{CC} is 0 V

9.4 Device Functional Modes

Table 1. Function Table

| INPUTS | | OUTPUT Y |
|-----------------|---|-------------|
| \overline{OE} | A | |
| L | H | H |
| L | L | L |
| H | X | Z |

10 Application and Implementation

10.1 Application Information

The SN74LVC1G125 device is a high drive CMOS device that can be used as a output enabled buffer with a high output drive, such as an LED application. It can produce 24 mA of drive current at 3.3 V making it Ideal for driving multiple outputs and good for high speed applications up to 100 MHz. The inputs are 5.5 V tolerant allowing it to translate down to V_{CC} .

10.2 Typical Application

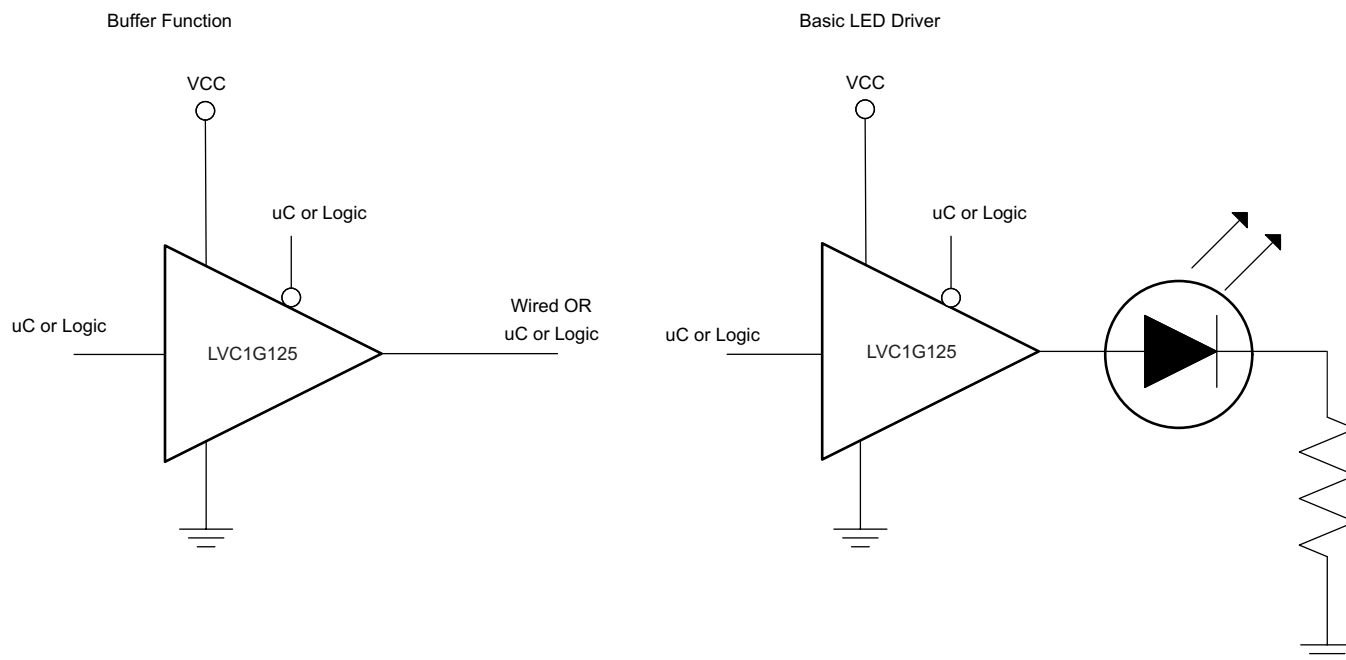


Figure 5. Application Schematic

10.2.1 Design Requirements

This device uses CMOS technology and has balanced output drive. Care should be taken to avoid bus contention because it can drive currents that would exceed maximum limits. The high drive will also create fast edges into light loads so routing and load conditions should be considered to prevent ringing.

10.2.2 Detailed Design Procedure

1. Recommended Input Conditions

- Rise time and fall time specs. See ($\Delta t/\Delta V$) in the [Recommended Operating Conditions](#) table.
- Specified high and low levels. See (V_{IH} and V_{IL}) in the [Recommended Operating Conditions](#) table.
- Inputs are overvoltage tolerant allowing them to go as high as (V_I max) in the [Recommended Operating Conditions](#) table at any valid V_{CC} .

2. Recommend Output Conditions

- Load currents should not exceed (I_O max) per output and should not exceed (Continuous current through V_{CC} or GND) total current for the part. These limits are located in the [Absolute Maximum Ratings](#) table.
- Outputs should not be pulled above V_{CC} .

Typical Application (continued)

10.2.3 Application Curves

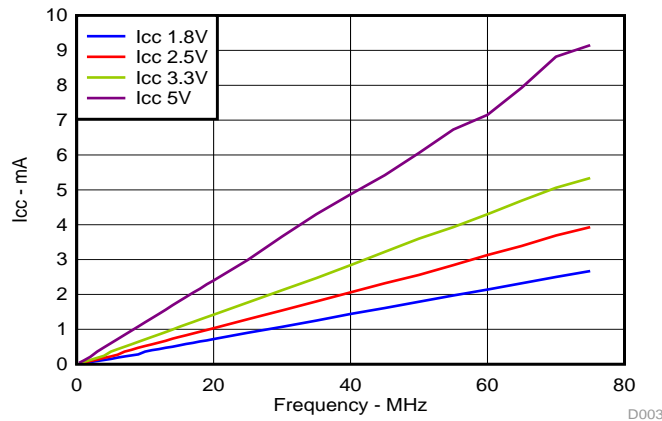


Figure 6. I_{CC} vs Frequency

11 Power Supply Recommendations

The power supply can be any voltage between the min and max supply voltage rating located in the [Recommended Operating Conditions](#) table.

Each VCC pin should have a good bypass capacitor to prevent power disturbance. For devices with a single supply a 0.1-μF capacitor is recommended and if there are multiple VCC pins then a 0.01-μF or 0.022-μF capacitor is recommended for each power pin. It is ok to parallel multiple bypass caps to reject different frequencies of noise. 0.1-μF and 1-μF capacitors are commonly used in parallel. The bypass capacitor should be installed as close to the power pin as possible for best results.

12 Layout

12.1 Layout Guidelines

When using multiple bit logic devices inputs should not ever float. In many cases, functions or parts of functions of digital logic devices are unused; for example, when only two inputs of a triple-input AND gate are used or only 3 of the 4 buffer gates are used. Such input pins should not be left unconnected because the undefined voltages at the outside connections result in undefined operational states. [Figure 7](#) shows the rules that must be observed under all circumstances. All unused inputs of digital logic devices must be connected to a high or low bias to prevent them from floating. The logic level that should be applied to any particular unused input depends on the function of the device. Generally they will be tied to GND or VCC, whichever makes more sense or is more convenient.

12.2 Layout Example

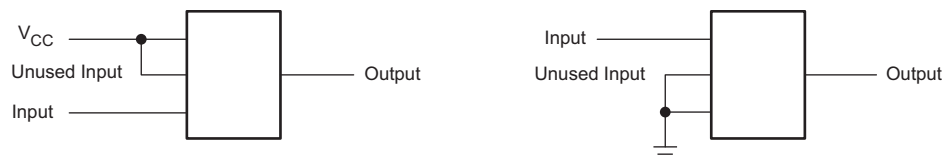


Figure 7. Package Layout

13 Device and Documentation Support

13.1 Trademarks

All trademarks are the property of their respective owners.

13.2 Electrostatic Discharge Caution



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

13.3 Glossary

[SLYZ022](#) — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

14 Mechanical, Packaging, and Orderable Information

The following pages include mechanical packaging and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead finish/ Ball material (6) | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|---------------|--------------|-----------------|------|-------------|------------------|--------------------------------------|----------------------|--------------|--------------------------------------|-------------------------|
| 74LVC1G125DBVRE4 | ACTIVE | SOT-23 | DBV | 5 | 3000 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 125 | (C255, C25F, C25J, C25K, C25R, C25T) | Samples |
| 74LVC1G125DBVRG4 | ACTIVE | SOT-23 | DBV | 5 | 3000 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 125 | (C255, C25F, C25J, C25K, C25R, C25T) | Samples |
| 74LVC1G125DBVTG4 | ACTIVE | SOT-23 | DBV | 5 | 250 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 125 | (C255, C25F, C25K, C25R) | Samples |
| 74LVC1G125DCKRE4 | ACTIVE | SC70 | DCK | 5 | 3000 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 125 | CM5 | Samples |
| 74LVC1G125DCKRG4 | ACTIVE | SC70 | DCK | 5 | 3000 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 125 | CM5 | Samples |
| 74LVC1G125DCKTE4 | ACTIVE | SC70 | DCK | 5 | 250 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 125 | CM5 | Samples |
| 74LVC1G125DCKTG4 | ACTIVE | SC70 | DCK | 5 | 250 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 125 | CM5 | Samples |
| 74LVC1G125DRLRG4 | ACTIVE | SOT-5X3 | DRL | 5 | 4000 | RoHS & Green | NIPDAUAG | Level-1-260C-UNLIM | -40 to 125 | (CM7, CMR) | Samples |
| SN74LVC1G125DBVR | ACTIVE | SOT-23 | DBV | 5 | 3000 | RoHS & Green | NIPDAU SN | Level-1-260C-UNLIM | -40 to 125 | (C255, C25F, C25J, C25K, C25R, C25T) | Samples |
| SN74LVC1G125DBVT | ACTIVE | SOT-23 | DBV | 5 | 250 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 125 | (C255, C25F, C25K, C25R) | Samples |
| SN74LVC1G125DCK3 | ACTIVE | SC70 | DCK | 5 | 3000 | RoHS & Non-Green | SNBI | Level-1-260C-UNLIM | -40 to 85 | (CMF, CMZ) | Samples |
| SN74LVC1G125DCKJ | ACTIVE | SC70 | DCK | 5 | 10000 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 125 | CM5 | Samples |
| SN74LVC1G125DCKR | ACTIVE | SC70 | DCK | 5 | 3000 | RoHS & Green | NIPDAU SN | Level-1-260C-UNLIM | -40 to 125 | (CM5, CMF, CMJ, CMK, CMR, CMT) | Samples |
| SN74LVC1G125DCKT | ACTIVE | SC70 | DCK | 5 | 250 | RoHS & Green | NIPDAU SN | Level-1-260C-UNLIM | -40 to 125 | (CM5, CMF, CMJ, CMK, CMR, CMT) | Samples |
| SN74LVC1G125DPWR | ACTIVE | X2SON | DPW | 5 | 3000 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 125 | R4 | Samples |
| SN74LVC1G125DRLR | ACTIVE | SOT-5X3 | DRL | 5 | 4000 | RoHS & Green | NIPDAU NIPDAUAG | Level-1-260C-UNLIM | -40 to 125 | (CM7, CMR) | Samples |
| SN74LVC1G125DRYR | ACTIVE | SON | DRY | 6 | 5000 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 125 | (CM, DM) | Samples |

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead finish/ Ball material (6) | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|---------------|--------------|--------------------|------|----------------|-----------------|--------------------------------------|----------------------|--------------|-------------------------|-------------------------|
| SN74LVC1G125DSFR | ACTIVE | SON | DSF | 6 | 5000 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 125 | CM | Samples |
| SN74LVC1G125YZPR | ACTIVE | DSBGA | YZP | 5 | 3000 | RoHS & Green | SNAGCU | Level-1-260C-UNLIM | -40 to 125 | (CM7, CMN) | Samples |

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF SN74LVC1G125 :

- Automotive: [SN74LVC1G125-Q1](#)
- Enhanced Product: [SN74LVC1G125-EP](#)

NOTE: Qualified Version Definitions:

- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects
- Enhanced Product - Supports Defense, Aerospace and Medical Applications

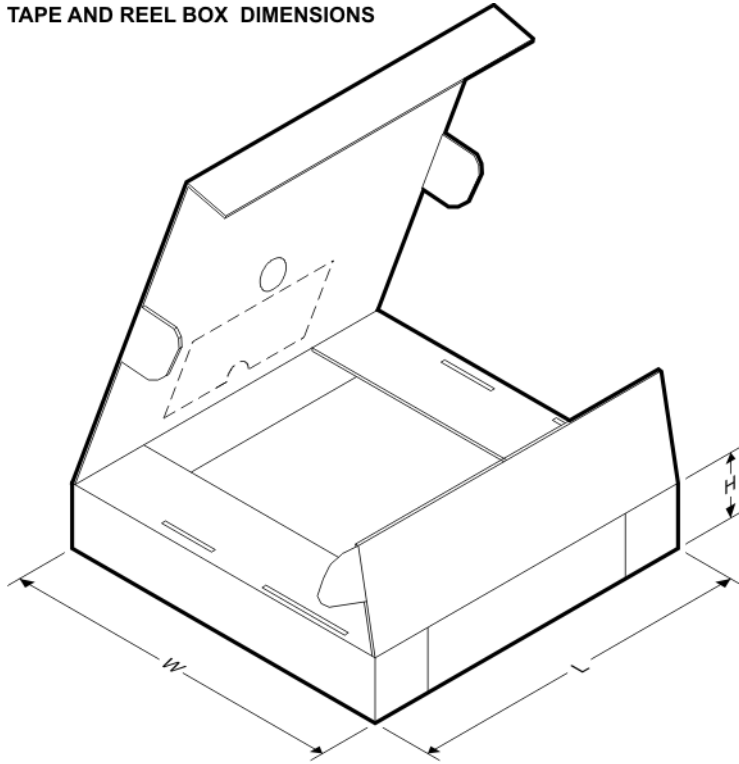
TAPE AND REEL INFORMATION



*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|------------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| 74LVC1G125DCKRG4 | SC70 | DCK | 5 | 3000 | 178.0 | 9.2 | 2.4 | 2.4 | 1.22 | 4.0 | 8.0 | Q3 |
| 74LVC1G125DCKTG4 | SC70 | DCK | 5 | 250 | 178.0 | 9.2 | 2.4 | 2.4 | 1.22 | 4.0 | 8.0 | Q3 |
| SN74LVC1G125DBVR | SOT-23 | DBV | 5 | 3000 | 178.0 | 9.0 | 3.23 | 3.17 | 1.37 | 4.0 | 8.0 | Q3 |
| SN74LVC1G125DBVR | SOT-23 | DBV | 5 | 3000 | 178.0 | 9.2 | 3.3 | 3.23 | 1.55 | 4.0 | 8.0 | Q3 |
| SN74LVC1G125DBVR | SOT-23 | DBV | 5 | 3000 | 180.0 | 8.4 | 3.23 | 3.17 | 1.37 | 4.0 | 8.0 | Q3 |
| SN74LVC1G125DBVT | SOT-23 | DBV | 5 | 250 | 178.0 | 9.2 | 3.3 | 3.23 | 1.55 | 4.0 | 8.0 | Q3 |
| SN74LVC1G125DBVT | SOT-23 | DBV | 5 | 250 | 180.0 | 8.4 | 3.23 | 3.17 | 1.37 | 4.0 | 8.0 | Q3 |
| SN74LVC1G125DCKR | SC70 | DCK | 5 | 3000 | 178.0 | 9.2 | 2.4 | 2.4 | 1.22 | 4.0 | 8.0 | Q3 |
| SN74LVC1G125DCKR | SC70 | DCK | 5 | 3000 | 180.0 | 8.4 | 2.47 | 2.3 | 1.25 | 4.0 | 8.0 | Q3 |
| SN74LVC1G125DCKR | SC70 | DCK | 5 | 3000 | 178.0 | 9.0 | 2.4 | 2.5 | 1.2 | 4.0 | 8.0 | Q3 |
| SN74LVC1G125DCKT | SC70 | DCK | 5 | 250 | 180.0 | 8.4 | 2.47 | 2.3 | 1.25 | 4.0 | 8.0 | Q3 |
| SN74LVC1G125DCKT | SC70 | DCK | 5 | 250 | 178.0 | 9.0 | 2.4 | 2.5 | 1.2 | 4.0 | 8.0 | Q3 |
| SN74LVC1G125DCKT | SC70 | DCK | 5 | 250 | 178.0 | 9.2 | 2.4 | 2.4 | 1.22 | 4.0 | 8.0 | Q3 |
| SN74LVC1G125DPWR | X2SON | DPW | 5 | 3000 | 178.0 | 8.4 | 0.91 | 0.91 | 0.5 | 2.0 | 8.0 | Q3 |
| SN74LVC1G125DRLR | SOT-5X3 | DRL | 5 | 4000 | 180.0 | 8.4 | 1.98 | 1.78 | 0.69 | 4.0 | 8.0 | Q3 |
| SN74LVC1G125DRYR | SON | DRY | 6 | 5000 | 180.0 | 9.5 | 1.15 | 1.6 | 0.75 | 4.0 | 8.0 | Q1 |
| SN74LVC1G125DSFR | SON | DSF | 6 | 5000 | 180.0 | 9.5 | 1.16 | 1.16 | 0.5 | 4.0 | 8.0 | Q2 |
| SN74LVC1G125YZPR | DSBGA | YZP | 5 | 3000 | 178.0 | 9.2 | 1.02 | 1.52 | 0.63 | 4.0 | 8.0 | Q1 |

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|------------------|--------------|-----------------|------|------|-------------|------------|-------------|
| 74LVC1G125DCKRG4 | SC70 | DCK | 5 | 3000 | 180.0 | 180.0 | 18.0 |
| 74LVC1G125DCKTG4 | SC70 | DCK | 5 | 250 | 180.0 | 180.0 | 18.0 |
| SN74LVC1G125DBVR | SOT-23 | DBV | 5 | 3000 | 180.0 | 180.0 | 18.0 |
| SN74LVC1G125DBVR | SOT-23 | DBV | 5 | 3000 | 180.0 | 180.0 | 18.0 |
| SN74LVC1G125DBVR | SOT-23 | DBV | 5 | 3000 | 202.0 | 201.0 | 28.0 |
| SN74LVC1G125DBVT | SOT-23 | DBV | 5 | 250 | 180.0 | 180.0 | 18.0 |
| SN74LVC1G125DBVT | SOT-23 | DBV | 5 | 250 | 202.0 | 201.0 | 28.0 |
| SN74LVC1G125DCKR | SC70 | DCK | 5 | 3000 | 180.0 | 180.0 | 18.0 |
| SN74LVC1G125DCKR | SC70 | DCK | 5 | 3000 | 202.0 | 201.0 | 28.0 |
| SN74LVC1G125DCKR | SC70 | DCK | 5 | 3000 | 180.0 | 180.0 | 18.0 |
| SN74LVC1G125DCKT | SC70 | DCK | 5 | 250 | 202.0 | 201.0 | 28.0 |
| SN74LVC1G125DCKT | SC70 | DCK | 5 | 250 | 180.0 | 180.0 | 18.0 |
| SN74LVC1G125DCKT | SC70 | DCK | 5 | 250 | 180.0 | 180.0 | 18.0 |
| SN74LVC1G125DPWR | X2SON | DPW | 5 | 3000 | 205.0 | 200.0 | 33.0 |
| SN74LVC1G125DRLR | SOT-5X3 | DRL | 5 | 4000 | 202.0 | 201.0 | 28.0 |
| SN74LVC1G125DRYR | SON | DRY | 6 | 5000 | 184.0 | 184.0 | 19.0 |
| SN74LVC1G125DSFR | SON | DSF | 6 | 5000 | 184.0 | 184.0 | 19.0 |
| SN74LVC1G125YZPR | DSBGA | YZP | 5 | 3000 | 220.0 | 220.0 | 35.0 |

DCK (R-PDSO-G5)

PLASTIC SMALL-OUTLINE PACKAGE



4093553-3/G 01/2007

- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
 - Falls within JEDEC MO-203 variation AA.

DCK (R-PDSO-G5)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
 - D. Publication IPC-7351 is recommended for alternate designs.
 - E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.

GENERIC PACKAGE VIEW

DRY 6

USON - 0.6 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



Images above are just a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.

4207181/G



USON - 0.6 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



4222894/A 01/2018

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

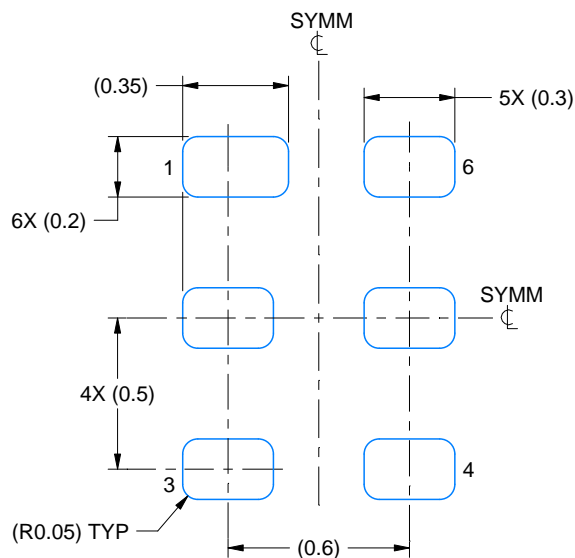
2. This drawing is subject to change without notice.

EXAMPLE BOARD LAYOUT

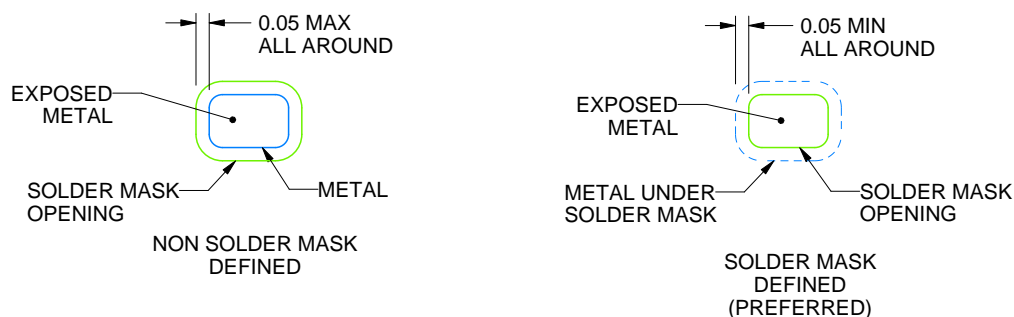
DRY0006A

USON - 0.6 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



LAND PATTERN EXAMPLE
1:1 RATIO WITH PKG SOLDER PADS
EXPOSED METAL SHOWN
SCALE:40X



SOLDER MASK DETAILS

4222894/A 01/2018

NOTES: (continued)

3. For more information, see QFN/SON PCB application report in literature No. SLUA271 (www.ti.com/lit/slue271).

EXAMPLE STENCIL DESIGN

DRY0006A

USON - 0.6 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



SOLDER PASTE EXAMPLE
BASED ON 0.075 - 0.1 mm THICK STENCIL
SCALE:40X

4222894/A 01/2018

NOTES: (continued)

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

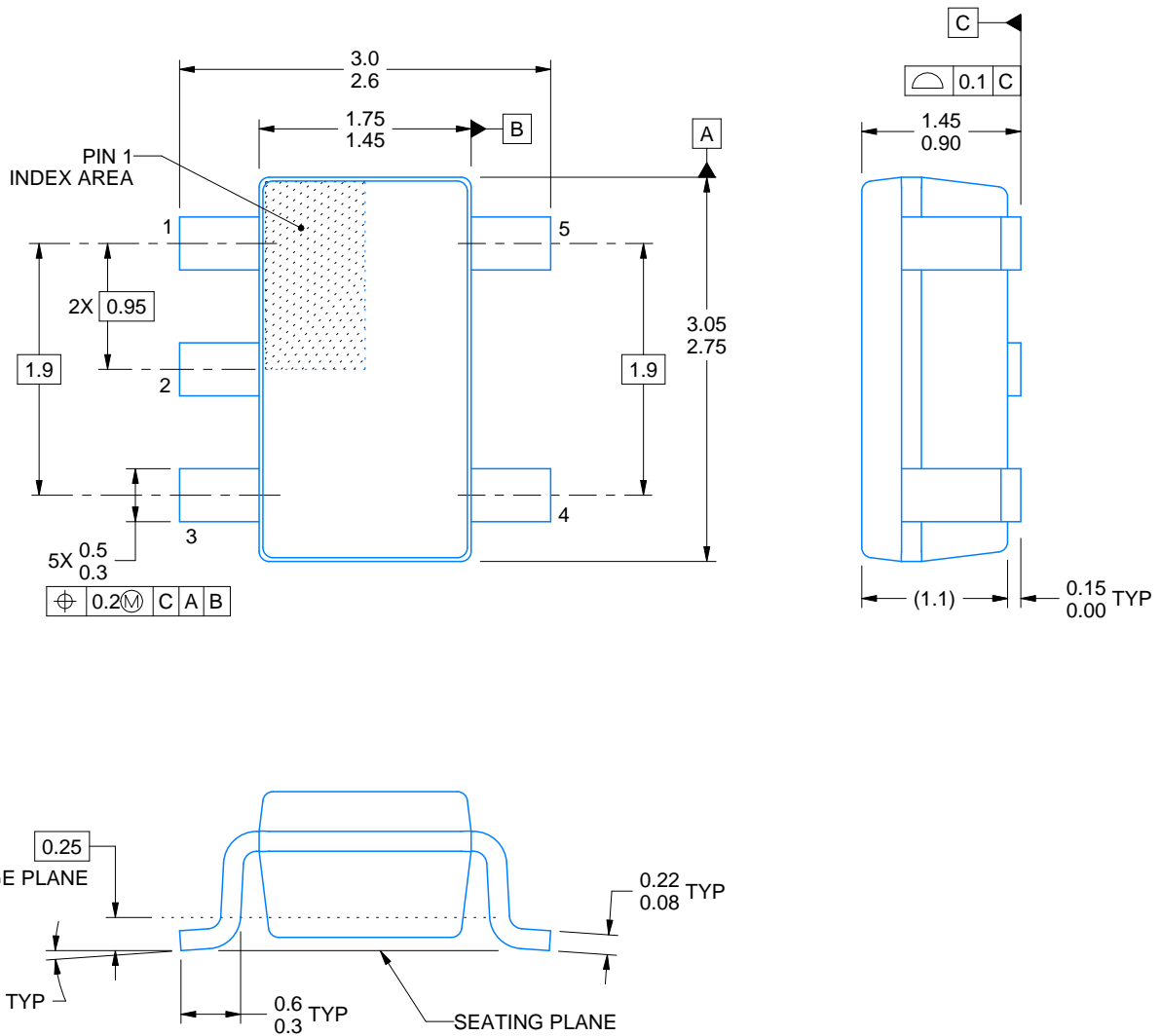


DBV0005A

PACKAGE OUTLINE

SOT-23 - 1.45 mm max height

SMALL OUTLINE TRANSISTOR



4214839/F 06/2021

NOTES:

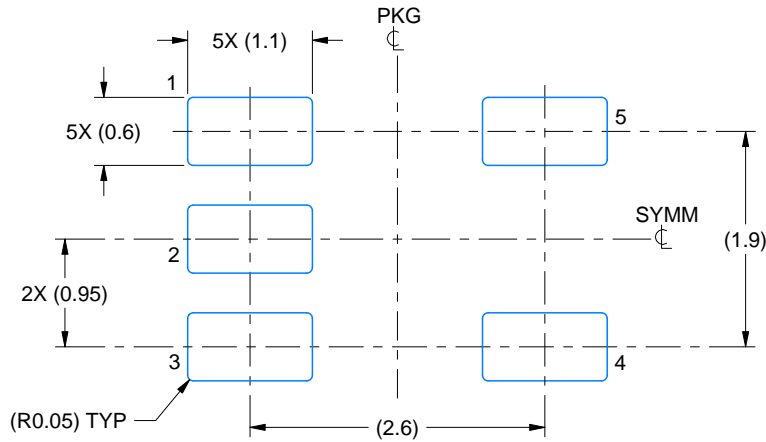
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Reference JEDEC MO-178.
4. Body dimensions do not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.25 mm per side.

EXAMPLE BOARD LAYOUT

DBV0005A

SOT-23 - 1.45 mm max height

SMALL OUTLINE TRANSISTOR



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:15X



SOLDER MASK DETAILS

4214839/F 06/2021

NOTES: (continued)

5. Publication IPC-7351 may have alternate designs.
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DBV0005A

SOT-23 - 1.45 mm max height

SMALL OUTLINE TRANSISTOR



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:15X

4214839/F 06/2021

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

GENERIC PACKAGE VIEW

DPW 5

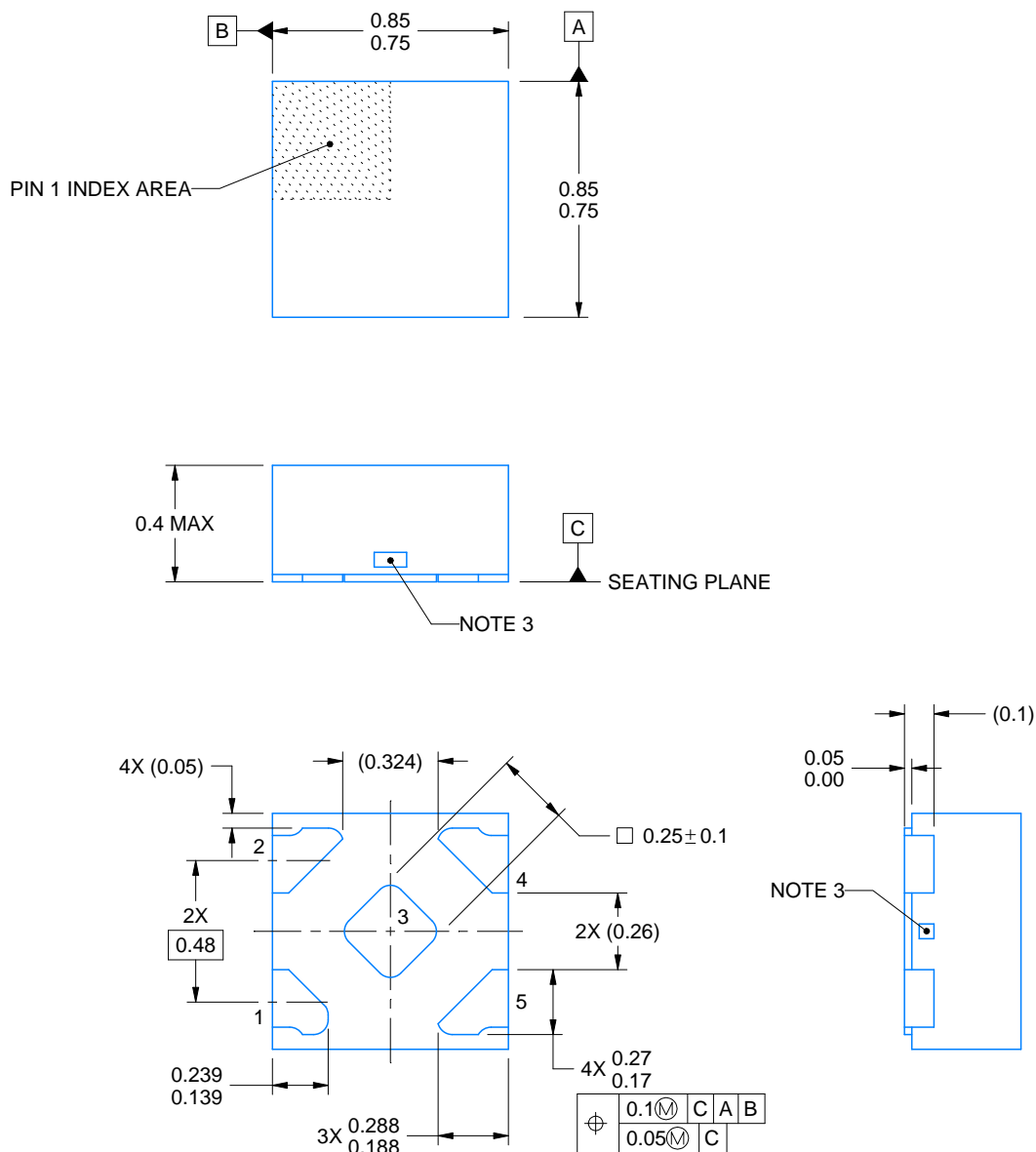
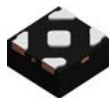
X2SON - 0.4 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



Images above are just a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.

4211218-3/D



4223102/D 03/2022

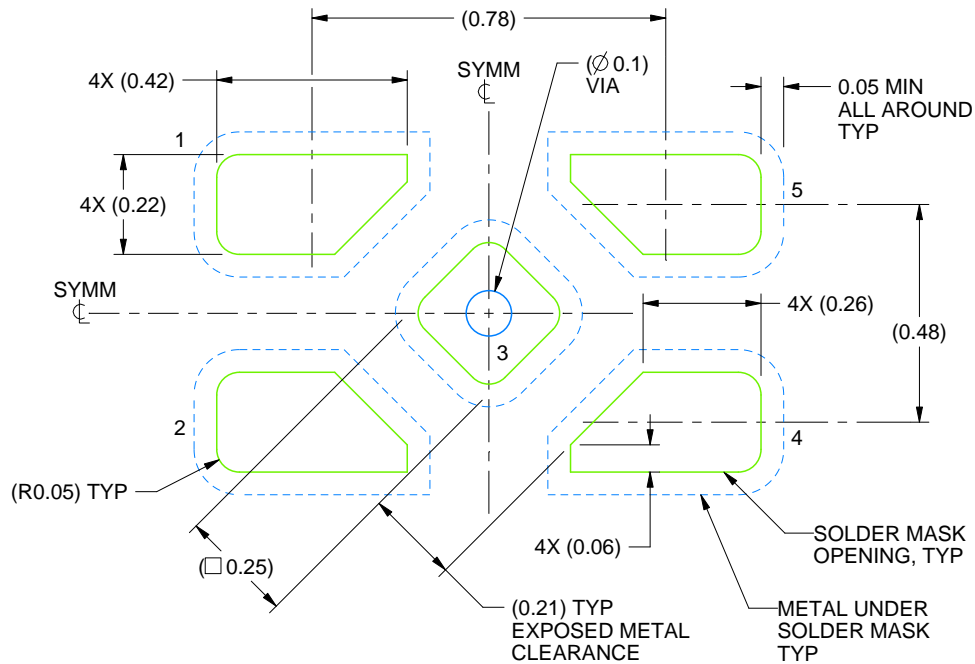
NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The size and shape of this feature may vary.

DPW0005A

X2SON - 0.4 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



LAND PATTERN EXAMPLE
SOLDER MASK DEFINED
SCALE:60X

4223102/D 03/2022

NOTES: (continued)

4. This package is designed to be soldered to a thermal pad on the board. For more information, refer to QFN/SON PCB application note in literature No. SLUA271 (www.ti.com/lit/slua271).

EXAMPLE STENCIL DESIGN

DPW0005A

X2SON - 0.4 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



SOLDER PASTE EXAMPLE
BASED ON 0.1 mm THICK STENCIL

EXPOSED PAD 3
92% PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE
SCALE:100X

4223102/D 03/2022

NOTES: (continued)

5. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

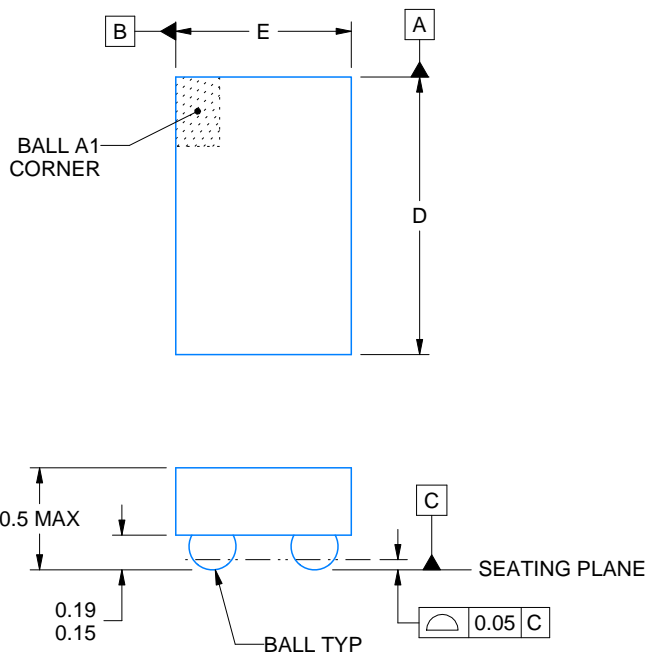
YZP0005



PACKAGE OUTLINE

DSBGA - 0.5 mm max height

DIE SIZE BALL GRID ARRAY



D: Max = 1.418 mm, Min = 1.358 mm

E: Max = 0.918 mm, Min = 0.858 mm

4219492/A 05/2017

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.

EXAMPLE BOARD LAYOUT

YZP0005

DSBGA - 0.5 mm max height

DIE SIZE BALL GRID ARRAY



LAND PATTERN EXAMPLE
SCALE:40X



SOLDER MASK DETAILS
NOT TO SCALE

4219492/A 05/2017

NOTES: (continued)

- Final dimensions may vary due to manufacturing tolerance considerations and also routing constraints. For more information, see Texas Instruments literature number SNVA009 (www.ti.com/lit/snva009).

EXAMPLE STENCIL DESIGN

YZP0005

DSBGA - 0.5 mm max height

DIE SIZE BALL GRID ARRAY



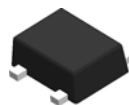
SOLDER PASTE EXAMPLE
BASED ON 0.1 mm THICK STENCIL
SCALE:40X

4219492/A 05/2017

NOTES: (continued)

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release.

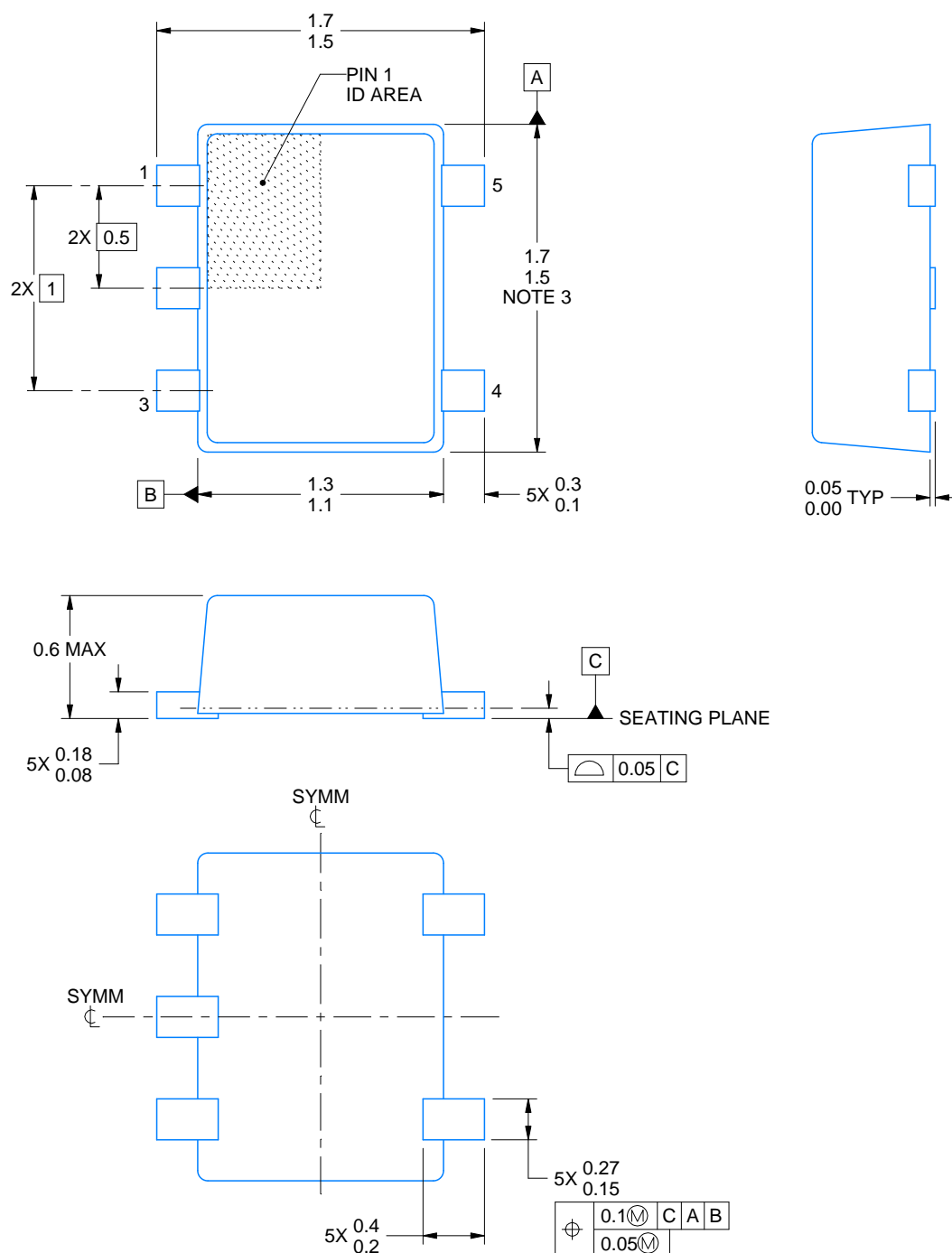
DRL0005A



PACKAGE OUTLINE

SOT - 0.6 mm max height

PLASTIC SMALL OUTLINE



4220753/B 12/2020

NOTES:

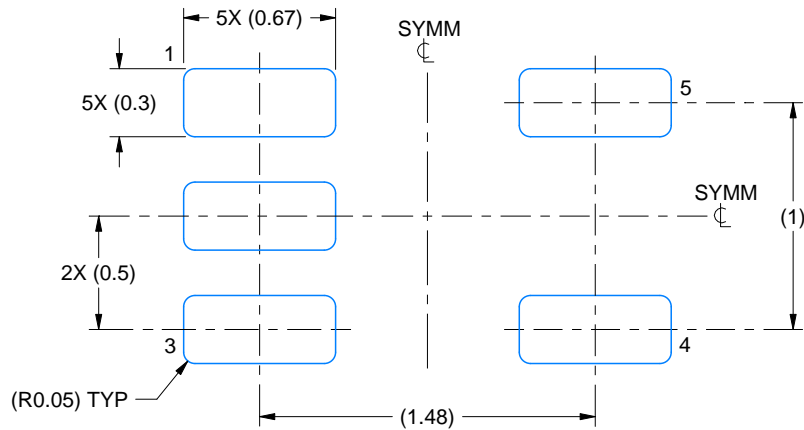
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. Reference JEDEC registration MO-293 Variation UAAD-1

EXAMPLE BOARD LAYOUT

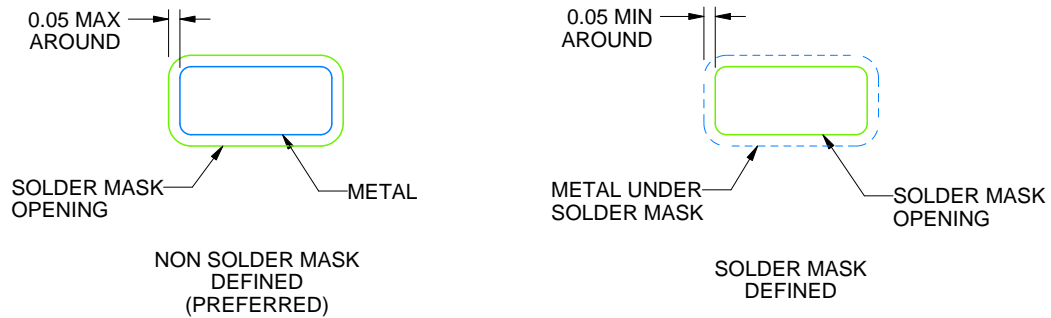
DRL0005A

SOT - 0.6 mm max height

PLASTIC SMALL OUTLINE



LAND PATTERN EXAMPLE
SCALE:30X



SOLDERMASK DETAILS

4220753/B 12/2020

NOTES: (continued)

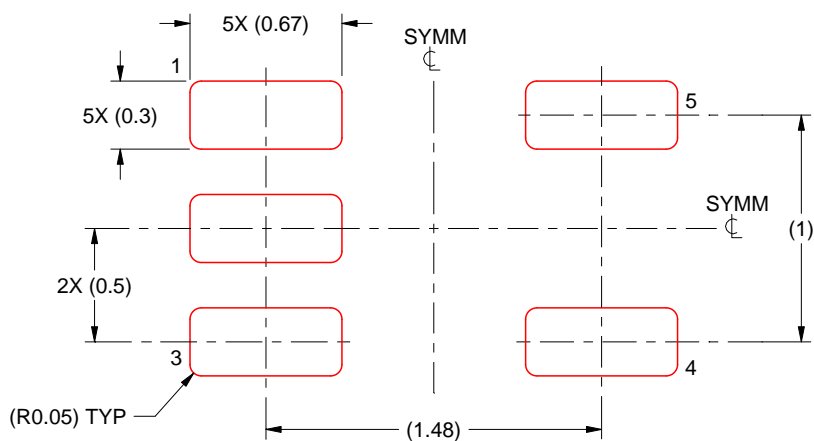
5. Publication IPC-7351 may have alternate designs.
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DRL0005A

SOT - 0.6 mm max height

PLASTIC SMALL OUTLINE



SOLDER PASTE EXAMPLE
BASED ON 0.1 mm THICK STENCIL
SCALE:30X

4220753/B 12/2020

NOTES: (continued)

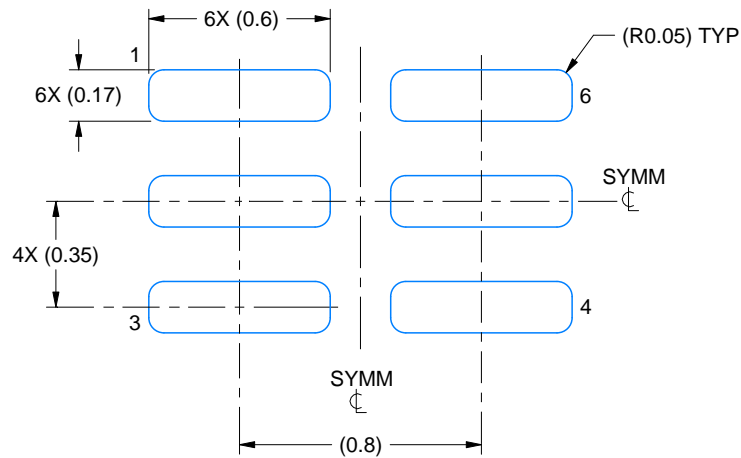
7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

EXAMPLE BOARD LAYOUT

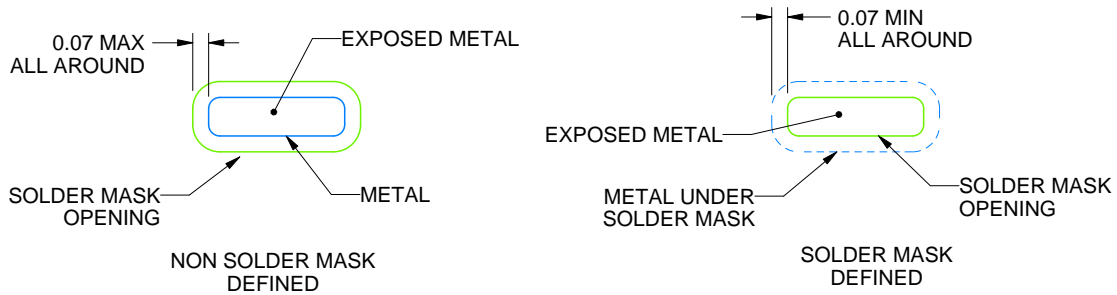
DSF0006A

X2SON - 0.4 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:40X



SOLDER MASK DETAILS

4220597/A 06/2017

NOTES: (continued)

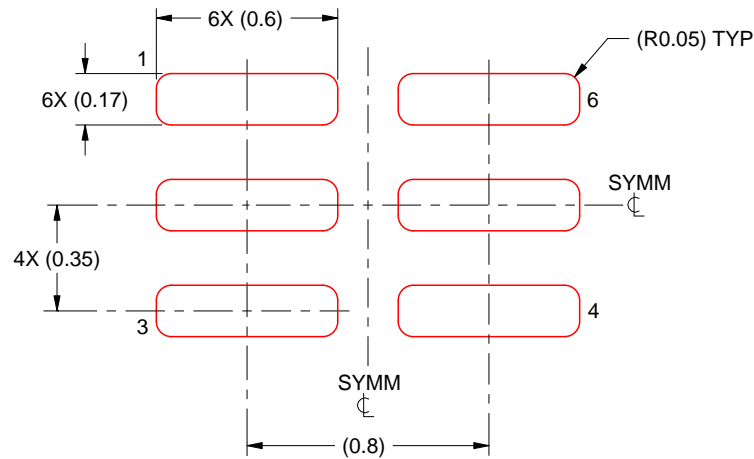
4. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slue271).

EXAMPLE STENCIL DESIGN

DSF0006A

X2SON - 0.4 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE
SCALE:40X

4220597/A 06/2017

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATA SHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to [TI's Terms of Sale](#) or other applicable terms available either on [ti.com](#) or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.

TI objects to and rejects any additional or different terms you may have proposed.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
Copyright © 2022, Texas Instruments Incorporated